

# Environmental Engineering

## Environmental Engineering

- Experience with all types of devices
  - > Discrete to RF, linear, memory to high end digital

## Burn-in development:

- Provide the most effective device stress
- Minimise the over and under shoot of the signal and power supply pins
- Ensure safe device operating temperature range
- Static BIAS of discrete and linear components
- Dynamic BIAS for most IC type components
  - > Effectively exercises the function of the device
  - > Standard: 24 unique signal, 1K of pattern depth, 1Mhz
  - > Address counters for memory burn-in
  - > Custom drivers with 48 unique signals and increased pattern depths up to 16 Meg.
  - > Dual board design using two oven slots to double capabilities
  - > Custom boards with frequencies up to 40Mhz

